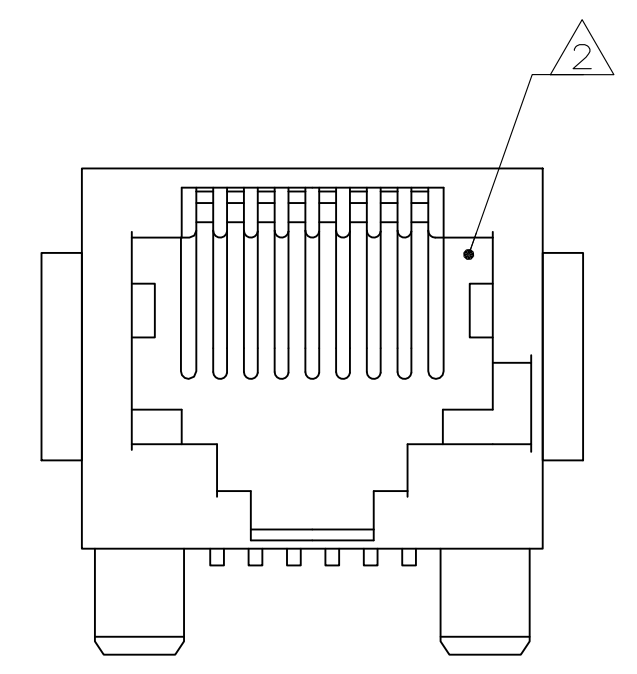
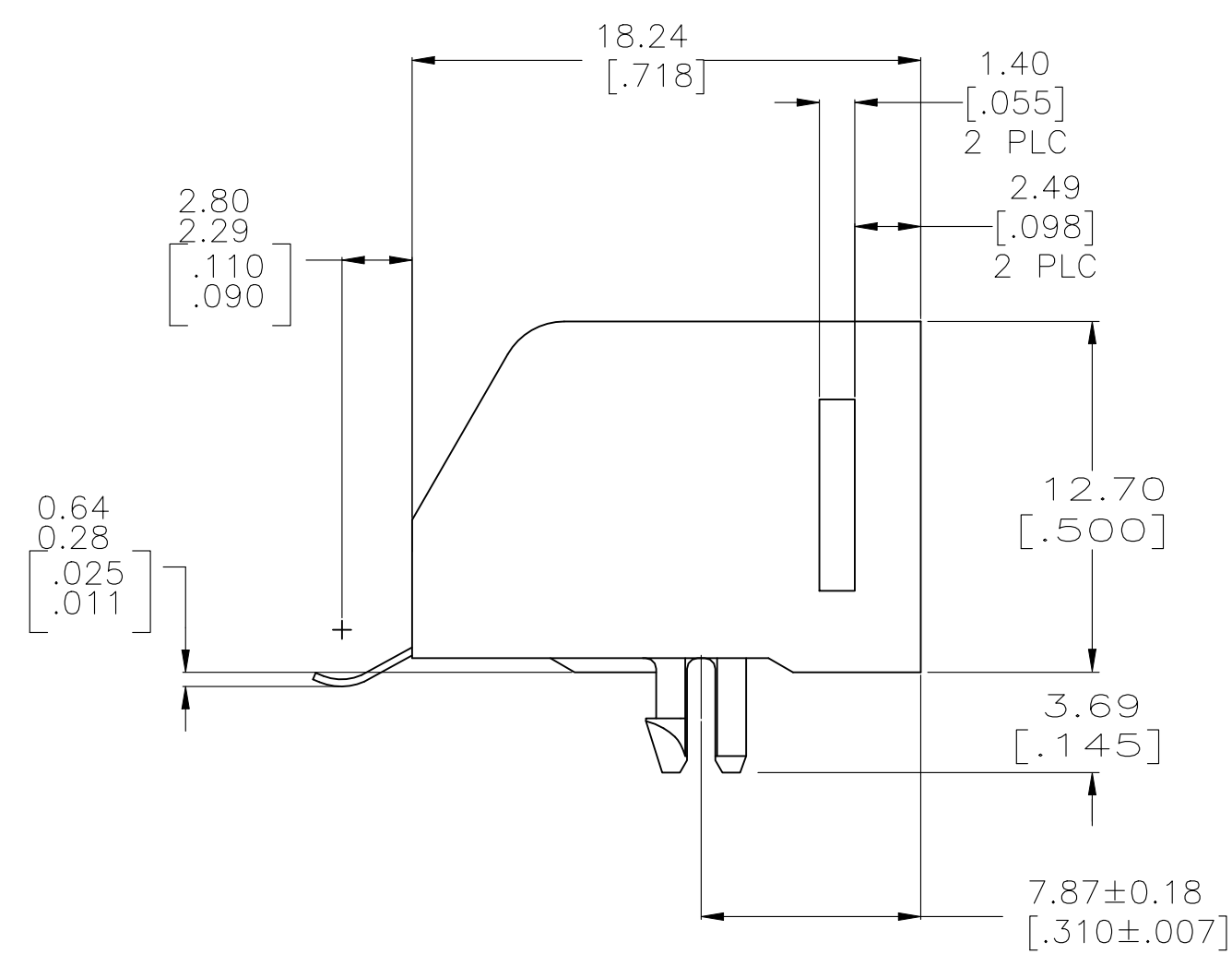
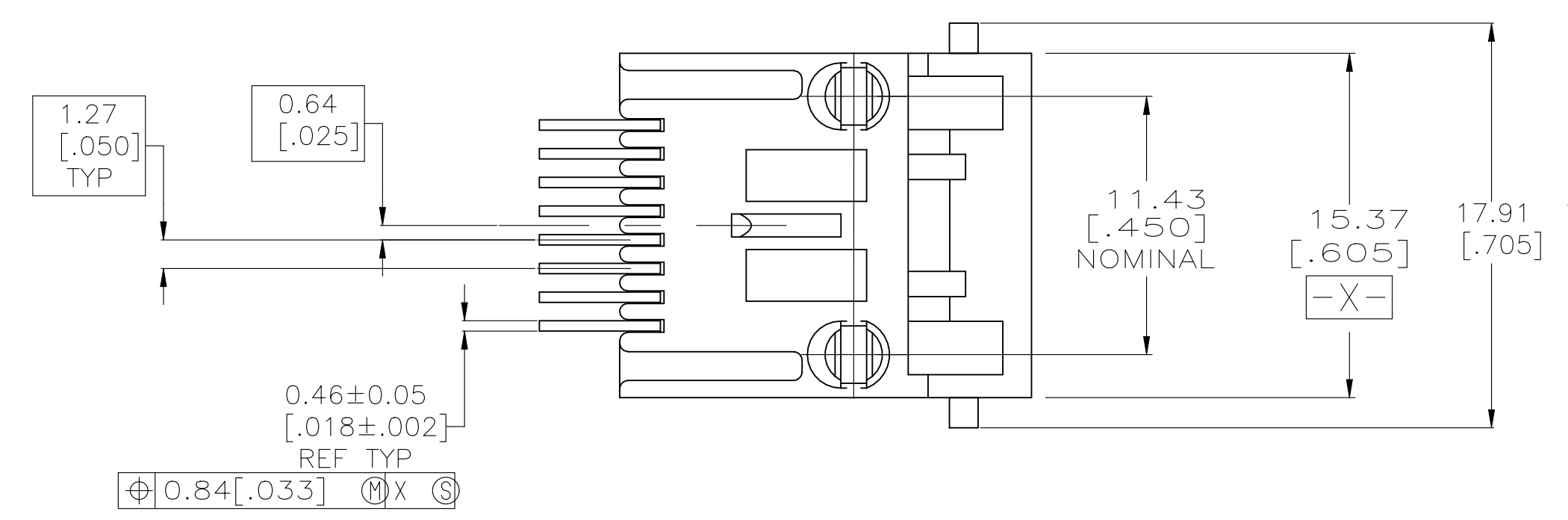


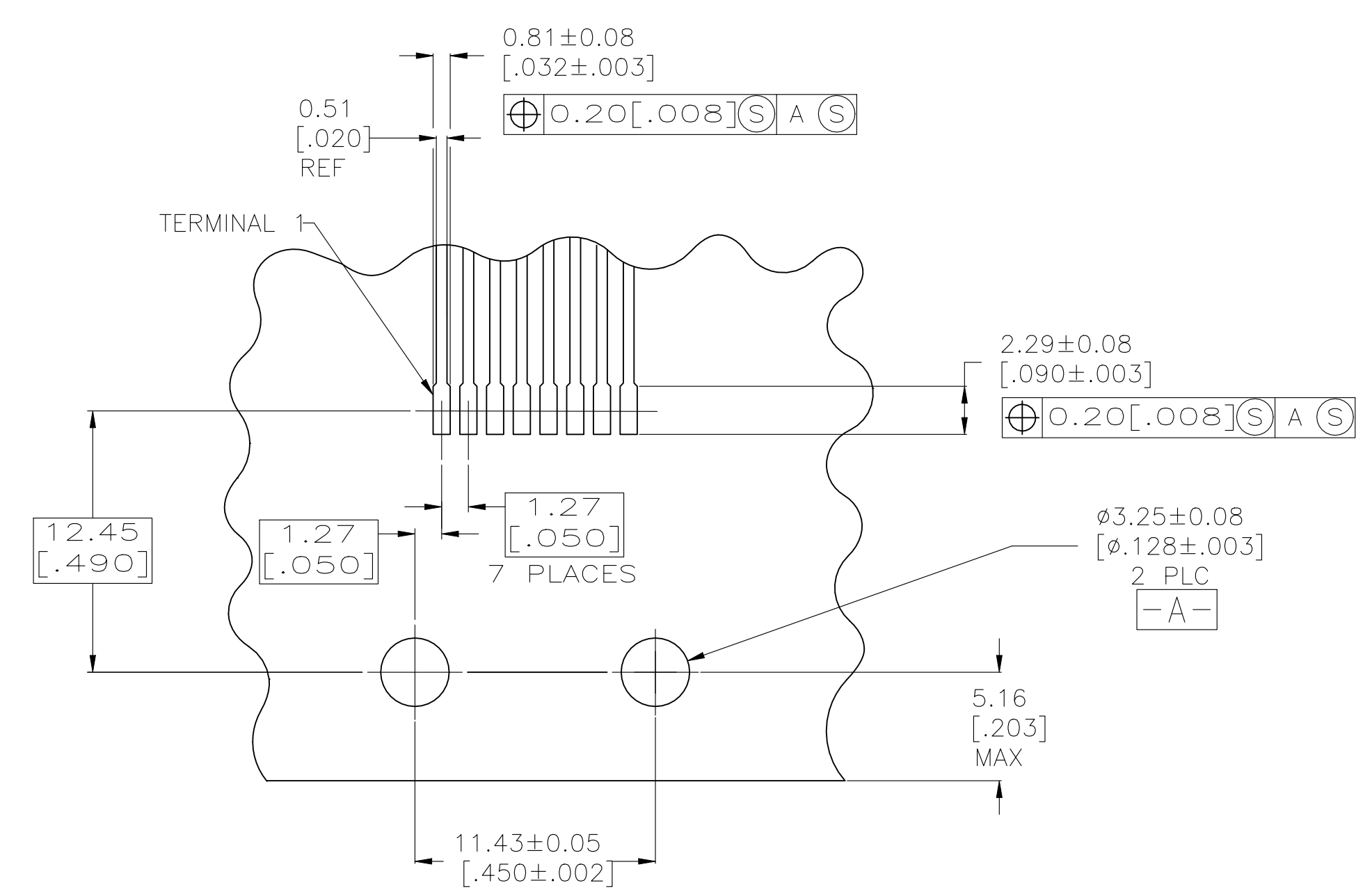
REVISIONS				
REV	DESCRIPTION	DATE	BY	APP'D
B1	REVISED AS PER ECN-22-180673	07NOV2022	KH	SZ



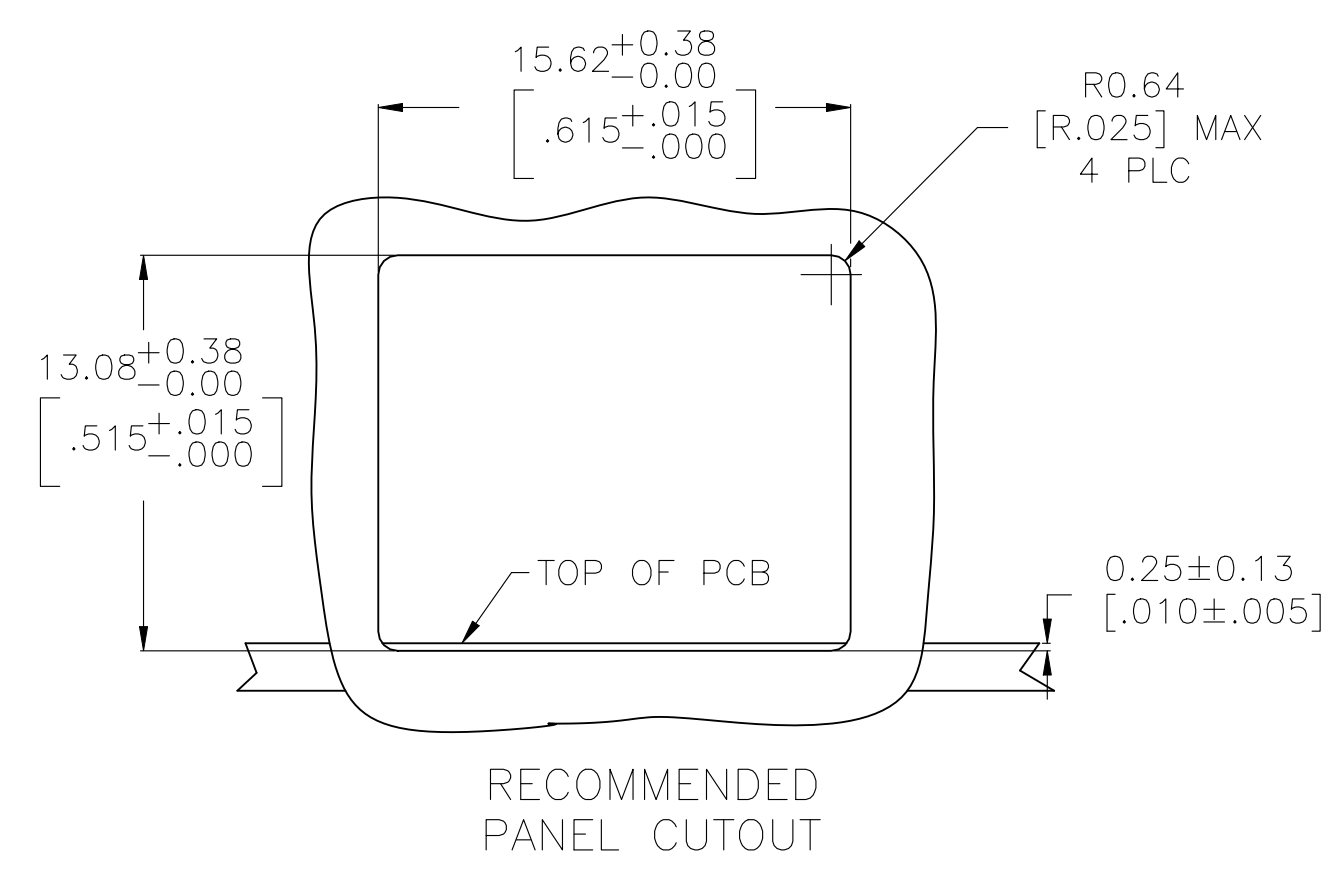
- MATERIAL: HOUSING – HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK.
TERMINAL – 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45–1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.



OBSOLETE



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE



8	5555078-1
NUMBER OF TERMINALS	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - 07JUN2005		TE Connectivity	
DIMENSIONS: mm [INCHES]		CIRK J. WESTMAN 07JUN2005			
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 07JUN2005		NAME MJ ASM, 8 POS	
0 PLC ± -		PRODUCT SPEC 108-1163		LOW PROFILE, R/A, SURFACE MOUNT, KEYED, WITH PANEL STOPS	
1 PLC ± -		APPLICATION SPEC 114-6040		SIZE CAGE CODE DRAWING NO RESTRICTED TO	
2 PLC ± -		WEIGHT 0.000000		A1 - C=5555078	
3 PLC ± -		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV B1	
4 PLC ± -					
ANGLES ± ± -					
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1			